



ML4950

Adjustable Output, Low Current Single Cell Boost Regulator with Detect

GENERAL DESCRIPTION

The ML4950 is a low power boost regulator designed for low voltage DC to DC conversion in single cell battery powered systems. The maximum switching frequency can exceed 100kHz, allowing the use of small, low cost inductors.

The combination of integrated synchronous rectification, variable frequency operation, and low supply current make the ML4950 ideal for single cell applications. The ML4950 is capable of start-up with input voltages as low as 1V, and the output voltage can be set anywhere between 2V and 3V.

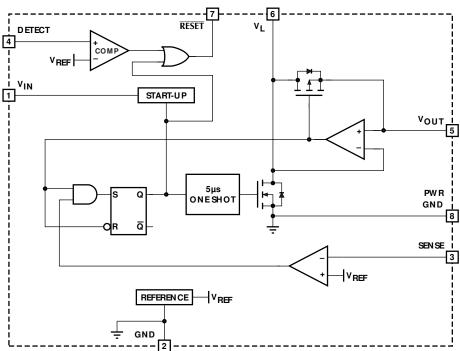
An integrated synchronous rectifier eliminates the need for an external Schottky diode and provides a lower forward voltage drop, resulting in higher conversion efficiency. In addition, low quiescent battery current and variable frequency operation result in high efficiency even at light loads. The ML4950 requires a minimum number of external components and is capable of achieving conversion efficiencies in excess of 90%.

The circuit also contains a RESET output which goes low when the IC can no longer function due to low input voltage, or when the DETECT input drops below 200mV.

FEATURES

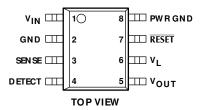
- Guaranteed full load start-up and operation at 1V input
- Pulse Frequency Modulation (PFM) and internal synchronous rectification for high efficiency
- Minimum external components
- Low ON resistance internal switching FETs
- Micropower operation
- Adjustable output voltage (2V to 3V)
- Low battery detect

BLOCK DIAGRAM



PIN CONFIGURATION

ML4950 8-Pin SOIC (S08)



PIN DESCRIPTION

PIN	NAME	FUNCTION	PIN	NAME	FUNCTION
1	V_{IN}	Battery input voltage	5	V_{OUT}	Boost regulator output
2	GND	Analog signal ground	6	V_{L}	Boost inductor connection
3	SENSE	Programming pin for setting the output voltage	7	RESET	Output goes low when regulation cannot be achieved, or when DETECT goes below 200mV
4	DETECT	Pulling this pin below 200mV causes the RESET pin to go low	8	PWR GND	

ABSOLUTE MAXIMUM RATINGS

Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

V _{OUT}	7V
Voltage on Any Other Pin GND - 0.3V	
Peak Switch Current (I _{PEAK})	1A
Average Switch Current (I _{AVG})	250mA
Junction Temperature	150°C
Storage Temperature Range	–65°C to 150°C
Lead Temperature (Soldering, 10 sec)	150°C
Thermal Resistance (θ_{IA})	

OPERATING CONDITIONS

Temperature Range	
ML4950CS-X	0°C to 70°C
ML4950ES-X	20°C to 70°C
V _{IN} Operating Range	
ML4950CS-X	1.0V to V _{OUT} - 0.2V
ML4950ES-X	1.1V to V _{OUT} - 0.2V
V _{OUT} Operating Range	2V to 3V

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, V_{IN} = Operating Voltage Range, T_A = Operating Temperature Range (Note 1)

SYMBOL	PARAM ETER	CONDITIONS	MIN	TYP	MAX	UNITS
SU PPLY						
I _{IN}	V _{IN} Current	$V_{IN} = V_{OUT} - 0.2V$		50	60	μΑ
I _{OUT(Q)}	V _{OUT} Quiescent Current			8	10	μΑ
$I_{L(Q)}$	V _L Quiescent Current				1	μΑ
PFM REGU	LATOR					
t _{ON}	Pulse Width		4.5	5	5.5	μs
V _{SENSE}	SENSE Compator Threshold Voltage		196	201	208	mV
	Load Regulation	See Figure 1 V _{IN} = 1.2V, I _{OUT} ≤ 25mA	2.425	2.5	2.575	V
	Undervoltage Lockout Threshold			0.85	0.95	V
RESETCO	MPARATOR				•	
	DETECT Threshold Voltage		194	200	206	mV
	DETECT Bias Current		-100		100	nA
	RESET Output High Voltage	I _{OH} = -100μA	V _{OUT} -0.2			V
	RESET Output Low Voltage	$I_{OL} = 100 \mu A$			0.2	V

Note 1: Limits are guaranteed by 100% testing, sampling, or correlation with worst-case test conditions.

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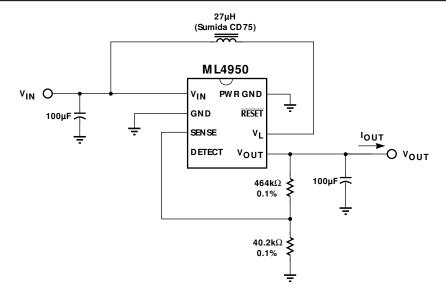


Figure 1. Application Test Circuit.

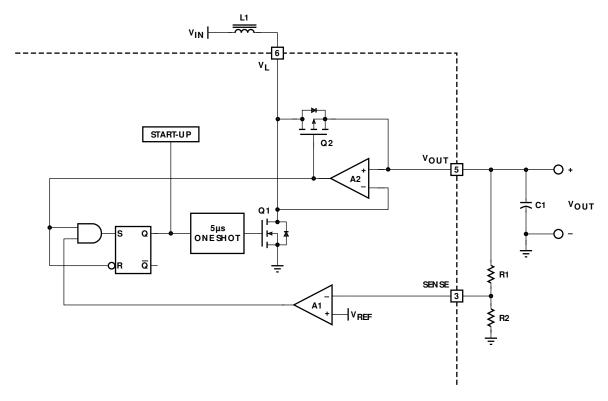


Figure 2. PFM Regulator Block Diagram.

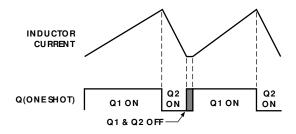


Figure 3. PFM Inductor Current Waveforms and Timing.

FUNCTIONAL DESCRIPTION

The ML4950 combines Pulse Frequency Modulation (PFM) and synchronous rectification to create a boost converter that is both highly efficient and simple to use. A PFM regulator charges a single inductor for a fixed period of time and then completely discharges before another cycle begins, simplifying the design by eliminating the need for conventional current limiting circuitry. Synchronous rectification is accomplished by replacing an external Schottky diode with an on-chip PMOS device, reducing switching losses and external component count.

REGULATOR OPERATION

A block diagram of the boost converter is shown in Figure 2. The circuit remains idle when V_{OUT} is at or above the desired output voltage, drawing $50\mu A$ from V_{IN} , and $8\mu A$ from V_{OUT} through the feedback resistors R1 and R2. When V_{OUT} drops below the desired output level, the output of amplifier A1 goes high, signaling the regulator to deliver charge to the output. Since the output of amplifier A2 is normally high, the flip-flop captures the A1 set signal and creates a pulse at the gate of the NMOS transistor Q1. The NMOS transistor will charge the inductor L1 for $5\mu s$, resulting in a peak current given by:

$$I_{L(PEAK)} = \frac{t_{ON} \times V_{IN}}{L1} = \frac{5\mu s \times V_{IN}}{L1}$$
 (1)

For reliable operation, L1 should be chosen so that $I_{L(PEAK)}$ does not exceed 1A.

When the one-shot times out, the NMOS transistor releases the V_L pin, allowing the inductor to fly-back and momentarily charge the output through the body diode of PMOS transistor Q2. But as the voltage across the PMOS transistor changes polarity, its gate will be driven low by the current sense amplifier A2, causing Q2 to short out its body diode. The inductor then discharges into the load through Q2. The output of A2 also serves to reset the flipflop and one-shot in preparation for the next charging cycle. A2 releases the gate of Q2 when its current falls to zero. If V_{OUT} is still low, the flip-flop will immediately initiate another pulse. The output capacitor (C1) filters the inductor current, limiting output voltage ripple. Inductor current and one-shot waveforms are shown in Figure 3.

RESET COMPARATOR

An additional comparator is provided to detect low V_{IN} or any other error condition that is important to the user. The inverting input of the comparator is internally connected to V_{REF} , while the non-inverting input is provided externally at the <u>DETECT</u> pin. The output of the comparator is the <u>RESET</u> pin, which swings from V_{OUT} to GND when an error is detected.

DESIGN CONSIDERATIONS

INDUCTOR

Selecting the proper inductor for a specific application usually involves a trade-off between efficiency and maximum output current. Choosing too high a value will keep the regulator from delivering the required output current under worst case conditions. Choosing too low a value causes efficiency to suffer. It is necessary to know the maximum required output current and the input voltage range to select the proper inductor value. The maximum inductor value can be estimated using the following formula:

$$L_{MAX} = \frac{V_{IN(MIN)}^2 \times t_{ON(MIN)} \times \eta}{2 \times V_{OUT} \times I_{OUT(MAX)}}$$
(2)

where η is the efficiency, typically between 0.8 and 0.9. Note that this is the value of inductance that just barely delivers the required output current under worst case conditions. A lower value may be required to cover inductor tolerance, the effect of lower peak inductor currents caused by resistive losses, and minimum dead time between pulses.

Another method of determining the appropriate inductor value is to make an estimate based on the typical performance curves given in Figures 4 and 5. Figure 4 shows maximum output current as a function of input voltage for several inductor values. These are typical performance curves and leave no margin for inductance and ON-time variations. To accommodate worst case conditions, it is necessary to derate these curves by at least 10% in addition to inductor tolerance.

For example, a single cell to $2.5\,\mathrm{V}$ application requires 20mA of output current while using an inductor with 15% tolerance. The output current should be derated by 25% to 25mA to cover the combined inductor and ON-time tolerances. Assuming that 1V is the end of life voltage of a single cell input, Figure 4 shows that with the ML4950 delivers 25mA at $2.5\,\mathrm{V}$ with a $27\mu\mathrm{H}$ inductor.

Figure 5 shows efficiency under the conditions used to create Figure 4. It can be seen that efficiency is mostly independent of input voltage and is closely related to inductor value. This illustrates the need to keep the inductor value as high as possible to attain peak system efficiency. As the inductor value goes down to $18\mu H$, the efficiency drops to between 75% and 80%. With $68\mu H$, the efficiency exceeds 90% and there is little room for improvement. At values greater than $100\mu H$, the operation of the synchronous rectifier becomes unreliable because the inductor current is so small that it is difficult for the control circuitry to detect. The data used to generate Figures 4 and 5 is provided in Table 1.

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DESIGN CONSIDERATIONS (Continued)

After the appropriate inductor value is chosen, it is necessary to find the minimum inductor current rating required. Peak inductor current is determined from the following formula:

$$I_{L(PEAK)} = \frac{t_{ON(MAX)} \times V_{IN(MAX)}}{L_{MIN}}$$
(3)

In the single cell application previously described, a maximum input voltage of 1.6V would give a peak current of 383mA. When comparing various inductors, it is important to keep in mind that suppliers use different criteria to determine their ratings. Many use a conservative current level, where inductance has dropped to 90% of its normal level. In any case, it is a good idea to try inductors of various current ratings with the ML4950 to determine which inductor is the best choice. Check efficiency and maximum output current, and if a current probe is available, look at the inductor current to see if it looks like the waveform shown in Figure 3. For additional information, see Application Note 29.

Suitable inductors can be purchased from the following suppliers:

Coilcraft (847) 639-6400

Coiltronics (561) 241-7876

Dale (605) 665-9301

Sumida (847) 956-0666

XFMRS, Inc. (317) 834-1066

OUTPUT CAPACITOR

The choice of output capacitor is also important, as it controls the output ripple and optimizes the efficiency of the circuit. Output ripple is influenced by three parameters: capacitance, ESR, and ESL. The contribution due to capacitance can be determined by looking at the change in capacitor voltage required to store the energy delivered by the inductor in a single charge-discharge cycle, as determined by the following formula:

$$\Delta V_{OUT} = \frac{t_{ON}^2 \times V_{IN}^2}{2 \times L \times C \times (V_{OUT} - V_{IN})}$$
(4)

For a 1.2V input, a 2.5V output, a $27\mu H$ inductor, and a $47\mu F$ capacitor, the expected output ripple due to capacitor value is 11mV.

Capacitor Equivalent Series Resistance (ESR) and Equivalent Series Inductance (ESL), also contribute to the output ripple due to the inductor discharge current waveform. Just after the NMOS transistor turns off, the output current ramps quickly to match the peak inductor current. This fast change in current through the output capacitor's ESL causes a high frequency (5ns) spike that can be over 1V in magnitude. After the ESL spike settles, the output voltage still has a ripple component equal to the inductor discharge current times the ESR. This component will have a sawtooth shape and a peak value equal to the peak inductor current times the ESR. ESR also has a negative effect on efficiency by contributing I²R losses during the discharge cycle.

An output capacitor with a capacitance of $100\mu F$, an ESR of less than 0.1Ω , and an ESL of less than 5nH is a good general purpose choice. Tantalum capacitors which meet these requirements can be obtained from the following suppliers:

AVX (207) 282-5111

Sprague (207) 324-4140

If ESL spikes are causing output noise problems, an EMI filter can be added in series with the output.

INPUT CAPACITOR

Unless the input source is a very low impedance battery, it will be necessary to decouple the input with a capacitor with a value of between $47\mu F$ and $100\mu F$. This prevents input ripple from affecting the ML4950 control circuitry, and it also improves efficiency by reducing I²R losses during the charge and discharge cycles of the inductor. Again, a low ESR capacitor (such as tantalum) is recommended.

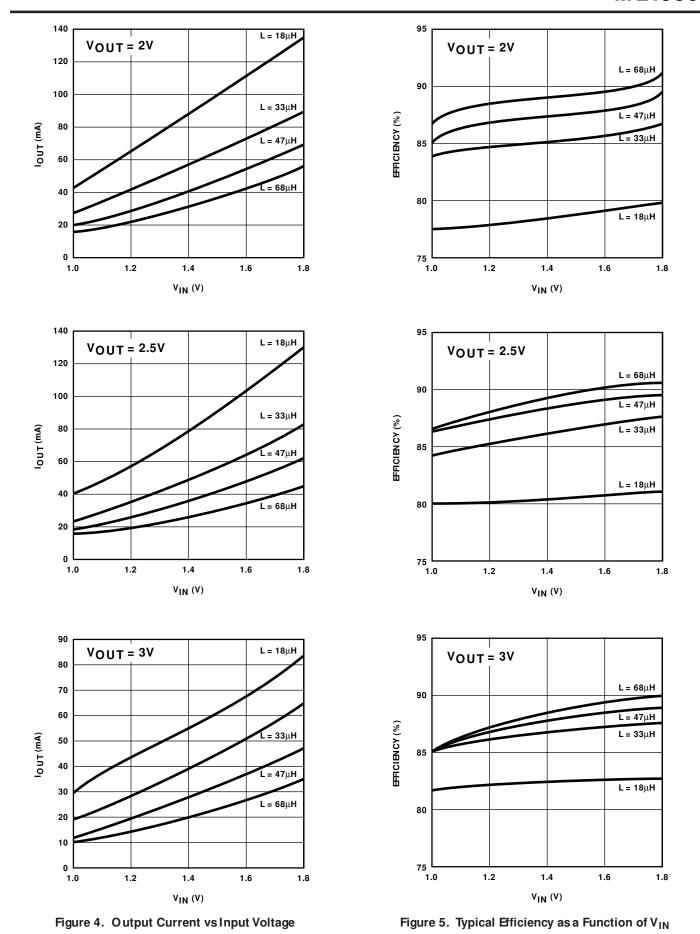
SETTING THE OUTPUT VOLTAGE

The adjustable output can be set to any voltage between 2V and 3V by connecting a resistor divider to the SENSE pin as shown in the block diagram. The resistor values R_1 and R_2 can be calculated using the following equation:

$$V_{OUT} = 0.2 \times \frac{(R_1 + R_2)}{R_2}$$
 (5)

The value of R_2 should be $40k\Omega$ or less to minimize bias current errors. R_1 is then found by rearranging the equation:

$$R_1 = R_2 \times \left(\frac{V_{\text{OUT}}}{0.2} - 1\right) \tag{6}$$



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DESIGN CONSIDERATIONS (Continued)

It is important to note that the accuracy of these resistors directly affects the accuracy of the output voltage. The SENSE pin threshold variation is $\pm 3\%$, and the tolerance of R_1 and R_2 will add to this to determine the total output variation.

Under some circumstances, input ripple cannot be reduced effectively. This occurs primarily in applications where inductor currents are high, causing excess output ripple due to "pulse grouping", where the charge-discharge pulses are not evenly spaced in time. In such cases it may be necessary to add a small 20pF to 100pF ceramic feedforward capacitor (C_{FF}) from the V_{IN} pin to the SENSE pin. This is particularly true if the ripple voltage at V_{IN} is greater than 100mV.

SETTING THE RESET THRESHOLD

To use the $\overline{\text{RESET}}$ comparator as an input voltage monitor, it is necessary to use an external resistor divider tied to the DETECT pin as shown in Figure 7. The resistor values R_A and R_B can be calculated using the following equation:

$$V_{\text{IN(MIN)}} = 0.2 \times \frac{\left(R_{\text{A}} + R_{\text{B}}\right)}{R_{\text{B}}} \tag{7}$$

The value of R_B should be $100k\Omega$ or less to minimize bias current errors. R_A is then found by rearranging the equation:

$$R_{A} = R_{B} \times \left(\frac{V_{\text{IN(MIN)}}}{0.2} - 1\right) \tag{8}$$

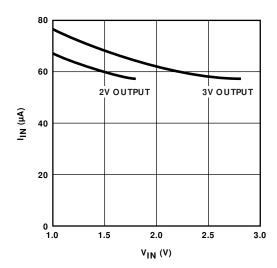


Figure 6. No Load Input Current vs. V_{IN} For 2V, R1 = 365k Ω , R2 = 40.2k Ω For 3V, R1 = 562k Ω , R2 = 40.2k Ω L = Sumida CD43, 22 μ H

LAYOUT

Good PC board layout practices will ensure the proper operation of the ML4950. Important layout considerations include:

- Use adequate ground and power traces or planes
- Keep components as close as possible to the ML4950
- Use short trace lengths from the inductor to the V_L pin and from the output capacitor to the V_{OUT} pin
- Use a single point ground for the ML4950 PWR GND pin and the input and output capacitors, and connect GND to PWR GND with a separate trace

A typical PC board layout is shown in Figure 8.

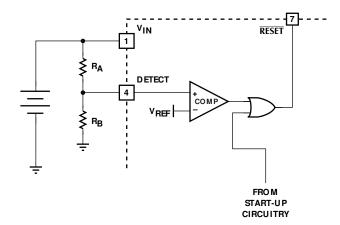


Figure 7. Battery Monitoring Circuit

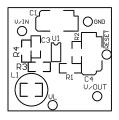






Figure 8. Typical PC Board Layout

V_{OUT} = **2V**

V _{IN}	I _{OUT} (mA)	EFFICIENCY (%)		
L = 18µH				
1.0	45.8	77.5		
1.2	65.8	78.0		
1.4	89.4	78.3		
1.6	111.7	78.9		
1.8	132.9	79.8		
L = 33µH				
1.0	27.9	83.6		
1.2	41.9	84.5		
1.4	57.8	85.0		
1.6	73.7	85.6		
1.8	89.8	86.4		
L = 47μH				
1.0	20.1	85.1		
1.2	31.6	86.6		
1.4	43.7	87.4		
1.6	57.5	87.5		
1.8	70.1	88.9		
L = 68µH				
1.0	14.9	86.5		
1.2	23.3	88.5		
1.4	32.6	89.1		
1.6	43.5	89.6		
1.8	54.6	90.9		

V_{OUT} = 2.5V

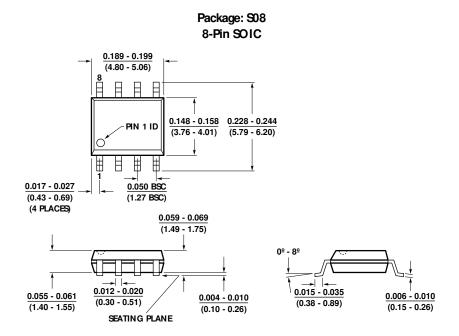
V _{IN}	I _{OUT} (mA)	EFFICIENCY (%)
L = 18μH		
1.0	38.3	80.0
1.2	54.5	80.2
1.4	74.6	80.5
1.6	98.5	80.8
1.8	124	81.0
L = 33µH		
1.0	22.7	84.2
1.2	33.0	85.2
1.4	47.0	86.0
1.6	61.8	86.6
1.8	79.3	87.0
L = 47μH		
1.0	16.4	86.2
1.2	24.1	87.1
1.4	33.4	88.1
1.6	46.1	89.0
1.8	58.6	89.5
L = 68µH		
1.0	12.6	86.4
1.2	17.4	87.9
1.4	25.2	89.2
1.6	33.9	90.1
1.8	43.8	90.9

 $V_{OUT} = 3V$

V_{IN}	I _{OUT} (mA)	EFFICIENCY (%)
L = 18µH	-	1
1.0	30.9	81.6
1.2	43.8	81.9
1.4	55.4	82.1
1.6	65.6	82.2
1.8	84.4	82.3
L = 33µH		
1.0	18.7	85.1
1.2	27.9	85.6
1.4	38.1	86.4
1.6	50.6	86.9
1.8	65.4	87.5
L = 47μH		
1.0	13.3	84.7
1.2	19.9	86.5
1.4	27.9	87.7
1.6	36.7	88.5
1.8	47.4	89.1
L = 68µH		
1.0	9.2	84.7
1.2	14.0	86.3
1.4	20.5	88.2
1.6	27.6	89.1
1.8	35.7	90.2

Table 1. Typical $I_{\mbox{\scriptsize OUT}}$ and Efficiency vs. $V_{\mbox{\scriptsize IN}}$

PHYSICAL DIMENSIONS inches (millimeters)



ORDERING INFORMATION

PART NUMBER	TEM PERATURE RANGE	PACKAGE
ML4950CS	0°C to 70°C	8-Pin SOIC (S08)
ML4950ES (Obsolete)	-20°C to 70°C	8-Pin SOIC (S08)

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